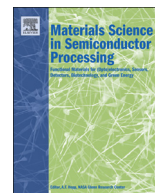




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A comparative electric and dielectric properties of Al/p-Si structures with undoped and Co-doped interfacial PVA layer

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ABSTRACT

In this study, Al/p-Si structures with undoped and Co-doped PVA interfacial layer called S_1 and S_2 were fabricated and their both electrical and dielectric properties were compared by using 300 kHz capacitance–voltage ($C-V$) and conductance–voltage ($G/\omega-V$) measurements at room temperature. Experimental results show that both C and G or dielectric constant (ϵ'), dielectric loss (ϵ'') values were found as strongly function of applied bias voltage especially at inverse and accumulation bias regions. It was found that the value of R_s considerably decreases with doping Co metal contrary to conductivity especially in the forward bias region. Such behavior can be attributed to the lack of free charges in pure PVA. The imaginary part of dielectric modulus (M'') gives two peaks for S_1 corresponding to enough reverse and forward biases and passes from a minimum at about zero bias. Also, it is clear that the minimum of the M'' for S_2 coincides with the maximum of the M'' for S_1 at zero bias. As a result, Co-doped PVA considerably improved the performance of structure. In addition, loss tangent ($\tan\delta$), ac conductivity (σ_{ac}) and real part of the electric modulus (M') were obtained and compared each other.

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1. Introduction

Polymeric materials have attracted much attention in both academic and industrial research fields as a consequence of their wide applications. Therefore, polymer electronics has attracted considerably interest in the last decades with the discovery of conducting polymers. The substantial attentiveness has given the production and electrical characterization of organic electronic devices such as metal-semiconductor (MS) and metal-polymer-semiconductor (MPS) type Schottky barrier diodes (SBDs) [1–8]. The use of polymers as dielectrics or interfacial layer between metal and semiconductor has attracted attention

in science and technology within the last decade [9–15]. Amongst them polyvinyl alcohol (PVA) has excellent film forming, emulsifying, and adhesive properties with low melting point for the fully hydrolyzed and partially hydrolyzed grades. Although it is also a good insulating material with low conductivity, but their conductivity can be increased by doping some metals such as nickel (Ni), and zinc (Zn), cobalt (Co) [16,17]. Therefore, metal doped PVA or other polymer materials can be used as an interfacial layer to reduce inter-diffusion at M/S interface [14,15].

Dielectric measurements such as the real (ϵ'), and imaginary (ϵ'') parts of complex dielectric constant and loss tangent ($\tan\delta = \epsilon''/\epsilon'$) are drastically affected by the presence dopant/dopants metal in the polymer [18,19]. It is well known PVA has a very high dielectric strength (> 1000 kV/mm), good charge storage capacity, and dopant-dependent electrical and optical properties [20].

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Electrical and dielectric properties of PVA are influenced not only by dopant structure and nature but also by doping concentration and procedure [21,22]. The performance of MS and MPS and similar devices are also considerably influenced by the production processes, the thickness of polymer layer and its homogeneity, surface charges or interface traps/states (N_{ss}) localized at M/S interface, series resistance of device (R_s). In the real MIS, MPS, and other structures, the localized interface states (N_{ss}) exist at semiconductor/insulator interface and the device behavior is different from ideal situation due to existence of the N_{ss} and R_s [13,23]. The effect of dipoles at the interface on dielectric properties is also important. Usually, the polarization can be classified in four categories namely: electronic (α_e) atomic/ionic (α_a), oriental/dipolar (α_o) and interfacial (α_i) [24–26] and each polarization mechanism involves a short range motion of the charge and contributes to total polarization of the material. Among them electronic polarization may be occurred at very high frequencies ($f > 10^{15}$ Hz). Atomic polarization may be occurred between 10^{10} and 10^{13} Hz. On the other hand, dipolar polarization can occur in intermediate or high frequencies ranges of 1 kHz–1 MHz due to their longer relaxation time and may originate from the existence of permanent orient-able dipoles, impurities and surface charges or this locations [24–26]. The interfacial polarization is more sensitive especially in the low frequencies ($f \leq 1$ kHz) [27]. Our measurements carried out 300 kHz. Therefore, last two types of polarizations may be dominant in our dielectric calculations. Especially, the interfacial polarization occurs when mobile charge carriers are impeded by a physical barrier that inhibits charge migration. Thus, the charges pile up at the barrier producing a localized polarization of the materials [27]. According to Tung [28], at a polycrystalline M/S interface, the bonding geometry likely changes from place to place, leading to a locally varying interface dipole. Therefore, the measured BH then reflects some weighted average of this interface dipole. So the Schottky dipole is assumed to arise from the polarization of interface bonds.

In this study, to comparative both the electrical and dielectric properties and ac electrical conductivity of Al/p-Si structures with undoped and Co-doped interfacial PVA layer called (Sample: S_1) and (Sample: S_2) were fabricated on the same wafer. The variation of both electrical and dielectric properties of these structures including dielectric constant (ϵ'), dielectric loss (ϵ''), loss tangent ($\tan\delta$), ac electrical conductivity (σ_{ac}) and real and imaginary parts of electric modulus (M' and M'') have been investigated over the applied bias voltage for 300 kHz at room temperature and compared each other. The experimental C–V and G/ω –V measurements were carried out in the wide range of voltage (–5 V to 6 V) by using an HP4192 A impedance analyzer at room temperature.

2. Experimental procedures

The Al/p-Si structures with and without Co-doped PVA interfacial layer were produced on p-type (B-doped) single crystal Si wafer with (1 1 1) float zone, 350 μm thickness, 0.04 Ωcm resistivity. First semiconductor wafer was cleaned

in a mix of a peroxide-ammoniac solution and also in $\text{H}_2\text{O} + \text{HCl}$ solution in 10 min. Si wafer was well rinsed in de-ionized water with 18 $\text{M}\Omega\text{cm}$ resistivity at ultrasonic bath for 15 min and then high purity Au (99.999%) with $\sim 2000 \text{ \AA}$ was thermally evaporated atop the back side of Si at about 10^{-6} Torr. To ensure a low resistivity ohmic contact, Si wafer was also annealed at 450 $^\circ\text{C}$ for 5 min in dry nitrogen (N_2) atmosphere. With undoped and Co-doped thin PVA film were produced on the p-type Si by electro-spinning method. 0.5 g of cobalt acetate was mixed with 1 g of polyvinyl Alcohol (PVA). After vigorous stirring for 2 h at 50 $^\circ\text{C}$, a viscous solution of with and without Co-doped PVA acetates were obtained.

Using a peristaltic syringe pump, the precursor solution was delivered to a metal needle syringe (10 ml) with an inner diameter of 0.9 mm at a constant flow rate of 0.02 ml/h. The needle was connected to a high voltage power supply and positioned in the perpendicular on a clamp. A piece of flat aluminum foil was placed 15 cm below the tip of the needle to collect the nano-fibers. By implementing a high bias voltage (20 kV) on the needle, a fluid jet was ejected from the tip. After electro-spinning process, rectifier contacts with 1 mm in diameter and 1500 Å thick high purity Al was deposited on the PVA surface through a metal shadow mask in high vacuum system at 10^{-6} Torr. The value of native SiO_2 and Co-doped PVA interfacial layers thickness (d_i) were obtained the interfacial layer capacitance at strong accumulation region ($C_i = \epsilon' \epsilon_0 A / d_i$) as 25.14 Å and 54.5 Å , respectively.

The C–V and G/ω –V measurements were carried out for 300 kHz at room temperature by using a HP 4192 A LF impedance analyzer between –5 V and 6 V dc voltages by 50 mV steps. At the same time, a small ac signal 40 $\text{mV}_{\text{p-p}}$ is applied to the sample in order to meet the requirement. All of these measurements were carried out with the help of a microcomputer through an IEEE-488 AC/DC converter card in the Janes-475 cryostat at about 10^{-3} Torr to avoid from any external noise or other effects.

3. Results and discussions

The forward and reverse-bias C and G/ω measurements of the Al/p-Si structures with undoped and Co-doped PVA interfacial layer called S_1 and S_2 were carried out at room temperature and given in Fig. 1(a) and (b), respectively. As can be seen in Fig. 1(a), the C–V plot of the S_2 for 300 kHz gives two peaks which are corresponding to the inversion and accumulation region. First peak especially can be attributed to a particular density distribution of D_{it} at M/S interface near the energy band gap of Si. The other especially can be attributed to the existence of R_s and interfacial Co-doped PVA layer. At the same time, the C–V plot of the S_1 for 300 kHz shows that capacitance increases with increasing voltage and gives a peak at depletion region due to the charges at traps [29,30]. On the contrary C–V plots, the G/ω –V plots show nearly a U shape behavior for both of the structures. It is easy to see that the values of the G/ω –V are 5.85×10^{-9} F for S_1 and 6.85×10^{-8} F for S_2 at –5 V, 3.67×10^{-10} F for S_1 and 1.27×10^{-8} F for S_2 at zero voltage, and 1.66×10^{-8} F for S_1

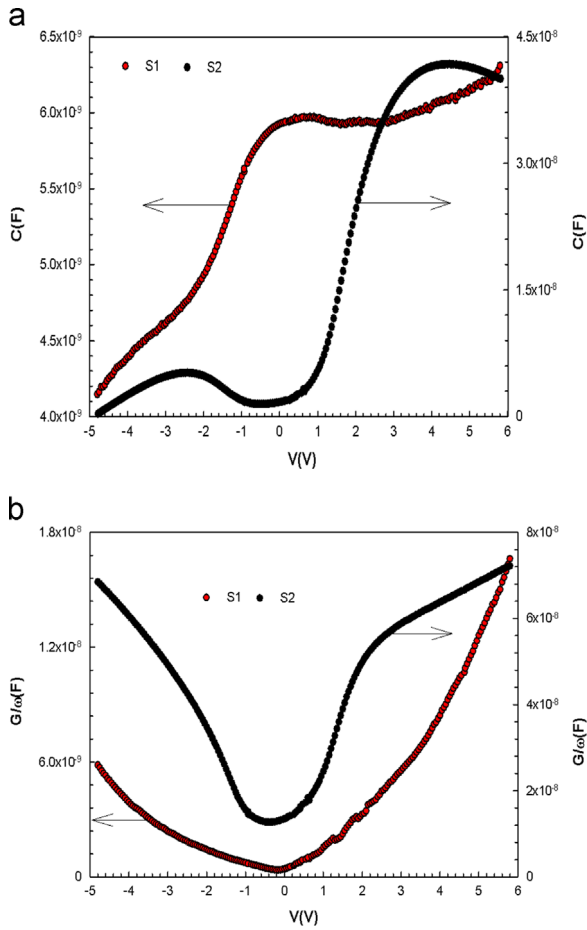


Fig. 1. The experimental (a) $C-V$ and (b) $G/\omega-V$ plots of the Al/p-Si structures with undoped (S_1) and Co-doped (S_2) PVA interfacial layer for 300 kHz at room temperature.

and 7.22×10^{-8} F for S_2 at +6 V, respectively. It is easy to decide that S_1 has higher conductivity than S_2 .

The value of R_s is effect both electrical and dielectric properties of these devices. For this reason, the voltage dependent of the resistance (R_i) of the Al/p-Si structures were obtained by using the C and G/ω data and admittance method. Using this method and accept that the real value of R_i at enough high frequencies and in strong accumulation region it corresponds to the real value of R_s for that kind of structures and can be computable from the measured C_{ma} and G_{ma} values as following [29],

$$R_s = \frac{G_{ma}}{G_{ma}^2 + \omega^2 C_{ma}^2} \quad (1)$$

where, ω ($=2\pi f$) is the angular frequency, C_{ma} and G_{ma} are the capacitance and conductance values in the strong accumulation region. The voltage dependent R_i values of S_1 and S_2 were extracted from Eq. (1) for 300 kHz and are given in Fig. 2. As can be seen in Fig. 2, the $R-V$ plots give a distinguishable peak at about zero bias corresponding to the minimum of the $G/\omega-V$ plots for S_1 . On the contrary S_1 , $R-V$ plots of the S_2 shows two peaks like $C-V$ plot for at reverse and strong accumulation regions due to particular

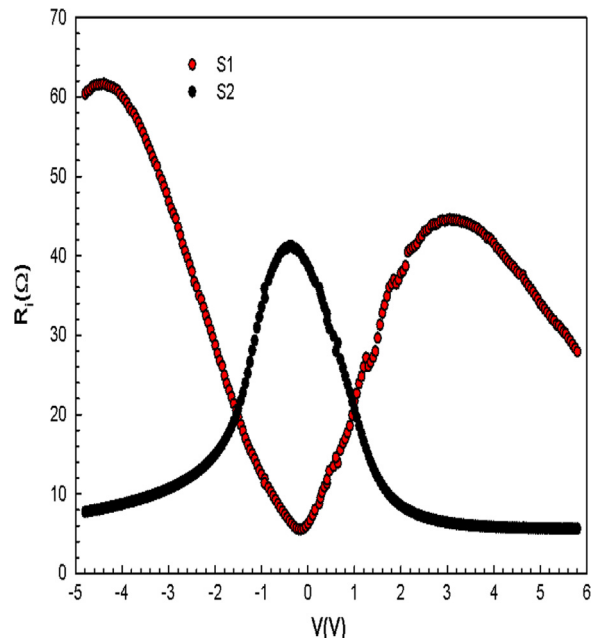


Fig. 2. The variation of the resistivity of the Al/p-Si structures with undoped (S_1) and Co-doped (S_2) PVA interfacial layer as a function bias voltage for 300 kHz at room temperature.

density distribution of N_{ss} and dopant metal (Co). It may also be restructure and reordering of N_{ss} and other surface charges under applied bias voltage/electric field. As can be clearly seen in Fig. 2, at enough high forward bias regions ($V \geq 6$ V) the real value of resistance corresponds to the R_s of structures. In addition the values of R_s for S_1 and S_2 samples were found as 27.23 Ω and 5.62 Ω at enough forward bias (6 V) at 300 kHz.

The dielectric constants (ϵ' and ϵ''), loss tangent ($\tan\delta$), ac-conductivity (σ_{ac}), and the real and imaginary parts of electric modulus (M' and M'') of the samples were determined using the following expressions [31]:

$$\epsilon^* = \epsilon' - j\epsilon'' = Cd/A\epsilon_0 - j(Gd/\omega A\epsilon_0) \quad (2)$$

$$\tan \delta = \epsilon''/\epsilon', \quad (3)$$

$$\sigma_{ac} = \omega\epsilon_0\epsilon' \tan \delta, \quad (4)$$

$$M^* = \frac{1}{\epsilon^*} = M' + jM'' = \frac{\epsilon'}{\epsilon'^2 + \epsilon''^2} + j\left(\frac{\epsilon''}{\epsilon'^2 + \epsilon''^2}\right) \quad (5)$$

where ω , d , ϵ_0 , and A quantities are the angular frequency, the thickness of the PVA, permittivity of the free space ($\epsilon_0=8.85 \times 10^{-14}$ F/cm), and the rectifier contact area, respectively. Both the obtained dielectric properties and electric modulus values as function of applied bias voltage for frequency of 300 kHz can purvey much information on conductivity contraction and relaxation process for some electronic applications [31,32]. The voltage dependent of ϵ' , ϵ'' , and $\tan\delta$ profiles were obtained using Eqs. 2 and 3, and are given in Fig. 3(a-c), respectively. As can be seen in these figures, the ϵ' , ϵ'' , and $\tan\delta$ values are strongly dependent on applied bias voltage for both of the samples. Our measurements carried out 300 kHz. Therefore, last

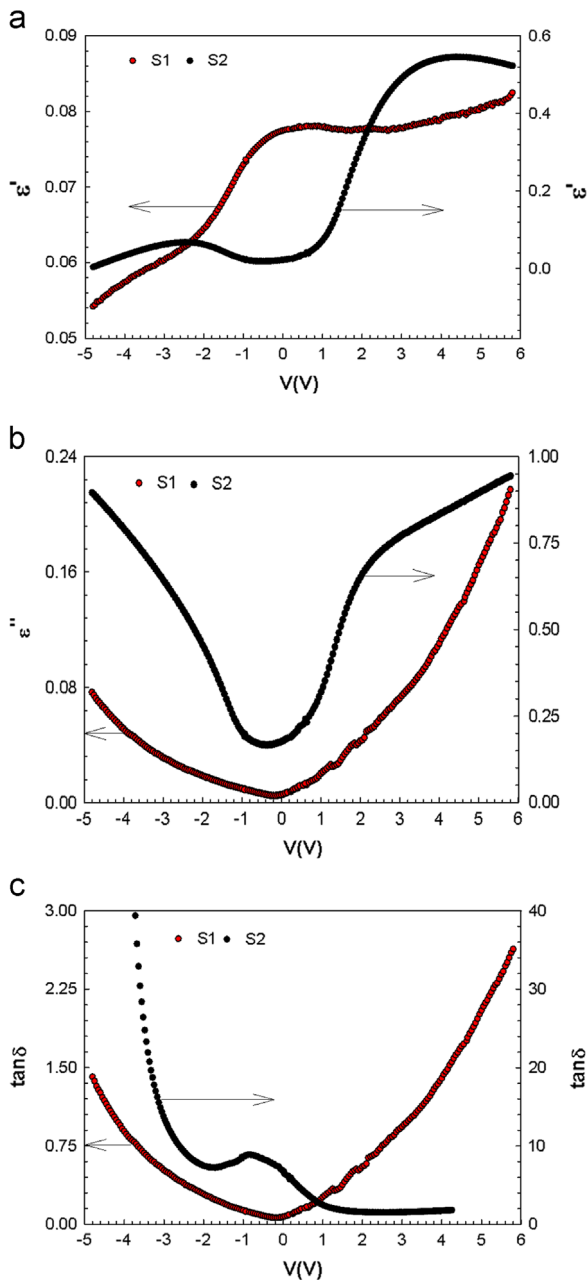


Fig. 3. Voltage dependence of the (a) ϵ' , (b) ϵ'' and (c) $\tan\delta$ of the Al/p-Si structures with undoped (S_1) and Co-doped (S_2) PVA interfacial layer for 300 kHz at room temperature.

two type's polarizations (oriental and interfacial) may be dominant in our dielectric calculations.

It is clear to see from these figures, ϵ' , ϵ'' , and $\tan\delta$ vs V profiles were found same as $C-V$ and $G/\omega-V$ plots due to same reasons for both of the samples. That kind of behaviors can be ascribed to the interfacial effects within bulk of the samples, interfacial polymer layers, interface traps, surface polarization, and the influences of electrodes [26,32,33].

The $\sigma_{ac}-V$ plots were also obtained from the conductivity data and are given in Fig. 4. As shown in this figure

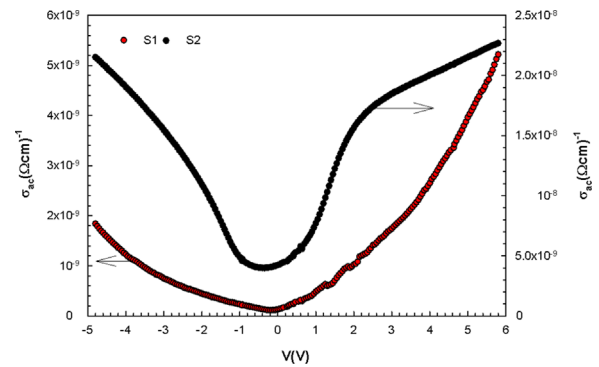


Fig. 4. Voltage dependence of the ac electrical conductivity (σ_{ac}) of the Al/p-Si structures with undoped (S_1) and Co-doped (S_2) PVA interfacial layer for 300 kHz at room temperature.

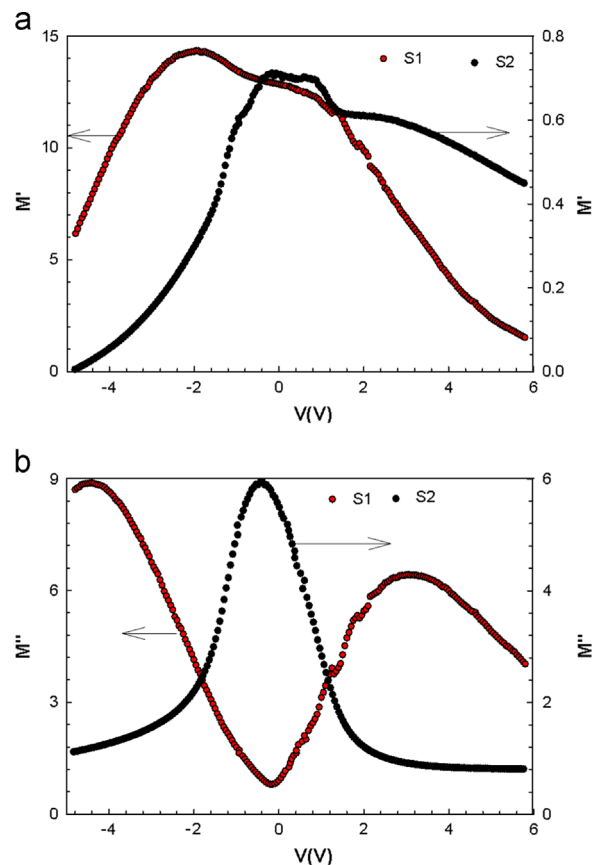


Fig. 5. (a) Real part M' and (b) imaginary part M'' of electric modulus M^* versus voltage over a measured the Al/p-Si structures with undoped (S_1) and Co-doped (S_2) PVA interfacial layer for 300 kHz at room temperature.

the voltage dependent value of σ_{ac} increases for S_2 . The increase in σ_{ac} with frequency conductivity accompanied by an increase of the eddy current which in turn increases the $\tan\delta$ due to gradual decrease in series resistance [34].

$M'-V$ and $M''-V$ plots were also obtained by using ϵ' and ϵ'' data for both of the samples and given in Fig. 5(a) and (b), respectively. Plots of the M' show a peak for each samples. The peak of S_1 is around -2 V and the other is around zero

bias voltage. In addition, Plot of the M'' shows two peaks for S_1 and a peak for S_2 . These properties of M' and M'' were attributed to the relaxation polarization in doped polymers and charges at traps. In polymer composite films, the existence of charges at traps gives rise to interfacial polarization. Therefore, it is believed that the dielectric relaxation process in the doped polymer is rather than ones of pure [35]. It is clear that the conductivity of S_2 (Co-doped) is higher than the S_1 , especially at inversion and accumulation regions. In these regions electric field is considerable high according to near zero bias voltage.

4. Conclusion

In this study, Al/p-Si structures with undoped and Co-doped PVA interfacial layer which are called S_1 and S_2 were fabricated on the same wafer and then dielectric parameters such as ϵ' , ϵ'' , $\tan\delta$, σ_{ac} , M' , and M'' were obtained by using 300 kHz capacitance–voltage ($C-V$) and conductance–voltage ($G/\omega - V$) measurements as function applied bias voltage for 300 kHz at room temperature. In addition, the resistivity of the both samples was obtained as function of applied bias voltage and its effects on dielectric properties were investigated and all properties of the both samples were compared with each other. Experimental results show that both C and G or dielectric constant (ϵ'), dielectric loss (ϵ'') values were found as strongly function of applied bias voltage especially at inverse and accumulation bias regions. It was found that the value of R_s considerably decreases with doping Co metal, contrary to conductivity especially in the forward bias region. Such behavior can be attributed to the lack of free charges in pure PVA. In addition, loss tangent ($\tan\delta$), ac conductivity (σ_{ac}) and real part of the electric modulus (M' and M'') were obtained and compared each other. The imaginary part of dielectric modulus (M'') gives two peaks for S_1 which are corresponding to enough reverse and forward biases and passes from a minimum at about zero bias. Also, it is clear that the minimum of the M'' for S_2 coincides with the maximum of the M'' for S_1 at zero bias. As a result, Co-doped PVA considerably improved the performance of structure. So, it is clear to see that S_2 shows better behavior than S_1 .

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